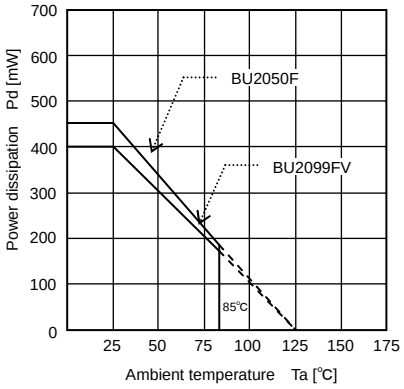
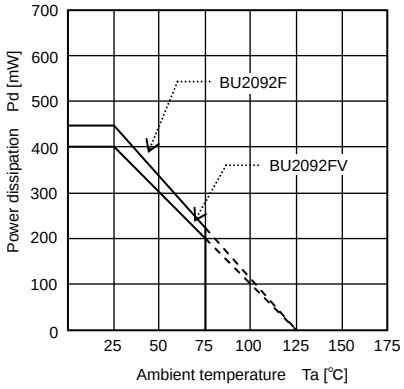
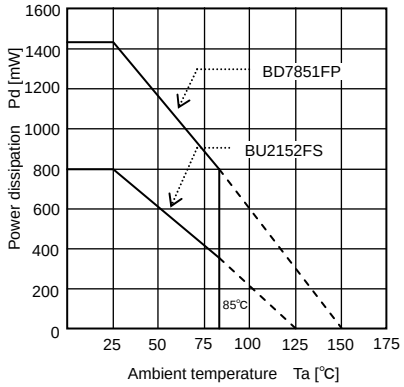
●Thermal derating curve







●Absolute maximum ratings (Ta=25℃)

Parameter	Symbol	Limits			Unit
		BU2050F	BU2092F	BU2092FV	
Power Supply Voltage	VDD	-0.3 to +7.0	-0.3 to +7.0		V
Power dissipation 1	Pd1	450 *1	450 (SOP) *2	400 (SSOPB) *3	mW
Power dissipation 2	Pd2	-	550 (SOP) *4	650 (SSOPB) *5	mW
Input Voltage	VIN	VSS-0.3 to VDD+0.5	VSS-0.3 to VDD+0.3		V
Output Voltage	Vo	VSS-0.3 to VDD+0.5	VSS to +25.0		V
Operating Temperature	Topr	-40 to +85	-25 to +75		℃
Storage Temperature	Tstg	-55 to +125	-55 to +125		℃

*1 Reduced by 4.5mW/℃ over 25℃
*2 Reduced by 4.5mW/℃ over 25℃
*3 Reduced by 4.0mW/℃ over 25℃
*4 Reduced by 5.5mW/℃ for each increase in Ta of 1℃ over 25℃ (When mounted on a board 50mm×50mm×1.6mm Glass-epoxy PCB).
*5 Reduced by 6.5mW/℃ for each increase in Ta of 1℃ over 25℃ (When mounted on a board 70mm×70mm×1.6mm Glass-epoxy PCB).

Parameter	Symbol	Limits			Unit
		BU2099FV	BD7851FP	BU2152FS	
Power Supply Voltage	VDD	-0.3 to +7.0	0 to +7.0	-0.3 to +7.0	V
Power dissipation 1	Pd1	400 (SSOPB) *6	1450 *7	800 *8	mW
Power dissipation 2	Pd2	650 (SSOPB) *9	-	-	mW
Input Voltage	VIN	VSS-0.3 to VDD+0.3	-0.3 to VCC+0.3	VSS-0.3 to VDD+0.3	V
Output Voltage	Vo	VSS to +25.0	0 to +10	VSS-0.3 to VDD+0.3	V
Operating Temperature	Topr	-40 to +85	-30 to +85	-25 to +85	℃
Storage Temperature	Tstg	-55 to +125	-55 to +150	-55 to +125	℃

*6 Reduced by 4.5mW/℃ over 25℃
*7 Reduced by 11.6mW/℃ over 25℃
*8 Reduced by 8.0mW/℃ over 25℃
*9 Reduced by 6.5mW/℃ for each increase in Ta of 1℃ over 25℃ (When mounted on a board 70mm×70mm×1.6mm Glass-epoxy PCB).

●Electrical characteristics

BU2050F (Unless otherwise noted, Ta=25℃, V_{DD}=4.5 to 5.5V)

Parameter	Symbol	Min.	Typ.	Max.	Unit	Condition
Power Supply Voltage	VDD	4.5	-	5.5	V	
Input high-level Voltage	VIH	0.7VDD	-	VDD	V	
Input low-level Voltage	VIL	VSS	-	0.3VDD	V	
Input Hysteresis	VHYS	-	0.5	-	V	
Output high-level Voltage	VOHD	VDD-1.5	-	VDD	V	IOH=-25mA
		VDD-1.0	-	VDD		IOH=-15mA
		VDD-0.5	-	VDD		IOH=-10mA
Output low-level Voltage	VOLD	VSS	-	1.5	V	IOL=25mA
		VSS	-	0.8		IOL=15mA
		VSS	-	0.4		IOL=10mA
Quiescent Current	IDD	-	-	0.1	mA	VIH=VDD, VIL=VSS

BU2092F/BU2092FV (Unless otherwise noted, Ta=25℃, V_{SS}=0V, V_{DD}=5.0V/3.0V)

Parameter	Symbol	Min.	Typ.	Max.	Unit	Condition
Power Supply Voltage	VDD	2.7	-	5.5	V	
Input high-level Voltage	VIH	3.5 / 2.5	-	-	V	VDD=5V/3V
Input low-level Voltage	VIL	-	-	1.5 / 0.4	V	VDD=5V/3V
Output low-level Voltage	VOL	-	-	2.0 / 1.0	V	VDD=5V/3V, IOL=20mA/5mA
Output high-level disable Current	IOZH	-	-	10.0	μA	VO=25.0V
Output low-level disable Current	IOZL	-	-	-5.0	μA	VO=0V
Quiescent Current	IDD	-	-	5.0 / 3.0	μA	VIN=VSS or VDD (VDD=5V/3V) OUTPUT:OPEN

BU2099FV (Unless otherwise noted, Ta=25℃, V_{SS}=0V, V_{DD}=5.0V/3.0V)

Parameter	Symbol	Min.	Typ.	Max.	Unit	Condition
Power Supply Voltage	VDD	2.7	-	5.5	V	
Input high-level Voltage	VIH	3.5 / 2.1	-	-	V	VDD=5V/3V
Input low-level Voltage	VIL	-	-	1.5 / 0.9	V	VDD=5V/3V
Output high-level Voltage (SO)	VOH	VDD-0.5 / VDD-0.3	-	-	V	VDD=5V/3V, IOH=-400μA/-100μA
Output low-level Voltage 1 (Qx)	VOL1	-	-	1.0	V	VDD=5V/3V, IOL1=10mA/5mA
		-	-	1.5		VDD=5V, IOL1=15mA
		-	-	2.0		VDD=5V, IOL1=20mA
Output low-level Voltage 2 (SO)	VOL2	-	-	0.4 / 0.3	V	VDD=5V/3V, IOL2=1.5mA/0.5mA
Output high-level disable Current (Qx)	IOZH	-	-	10	μA	VO=25.0V
Output low-level disable Current (Qx)	IOZL	-	-	-5.0	μA	VO=0V
IPULLDOWN ($\overline{OE}$)	IPD	-	-	150 / 60	μA	$\overline{OE}$= VDD, VDD=5V/3V
Low Voltage Reset	VCLR	1.1	-	2.4	V	
Quiescent Current	IDD	-	-	200	μA	VIN=VSS or VDD, VDD=5V OUTPUT:OPEN

●Electrical characteristics

BD7851FP (Unless otherwise noted, Ta=25℃, V_{CC}=5.0V)

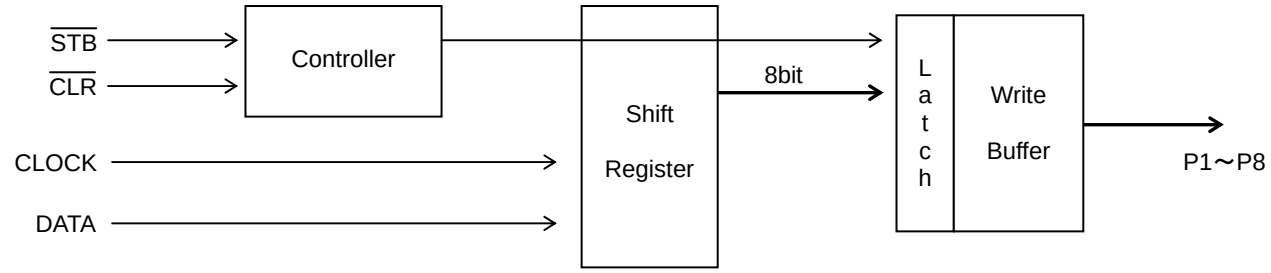
Parameter	Symbol	Min.	Typ.	Max.	Unit	Condition
Power Supply Voltage	VDD	4.5	-	5.5	V	
Input high-level Voltage	VIH	0.8×VCC	-	-	V	
Input low-level Voltage	VIL	-	-	0.2×VCC	V	
Output high-level Voltage	VOH	VCC-0.5	-	-	V	IOH=-1mA
Output low-level Voltage	VOL	-	-	0.5	V	IOL=1mA
Quiescent Current	ICC	-	0.7	1.0	mA	R=13kΩ OUT1～OUT16:OFF
		-	1.8	3.0	mA	R=1.3kΩ OUT1～OUT16:OFF
		-	4.0	6.5	mA	R=13kΩ OUT1～OUT16:ON
		-	30	40	mA	R=1.3kΩ OUT1～OUT16:ON
Reference Current Output Current (including the equation between each bit)	Iolc1	48	55	62	mA	VOUT=2.0V, R=1.3kΩ
	Iolc2	5.0	5.9	6.8	mA	VOUT=2.0V, R=13kΩ
Equation between each bit of Reference Current Output Current	Δiolc	-	±1	±6	%	VOUTn=2.0V, R=1.3kΩ (1bit : ON)
Change rate of reference current output current for output voltage	IΔVCC	-	±1	±6	%/V	VOUT=2.0 to 3.0V, R=1.3kΩ
Output Leak Current	IOH	-	0.01	0.8	μA	VOUT=10V

BU2152FS (Unless otherwise noted, Ta=25℃, V_{DD}=2.7 to 5.5V)

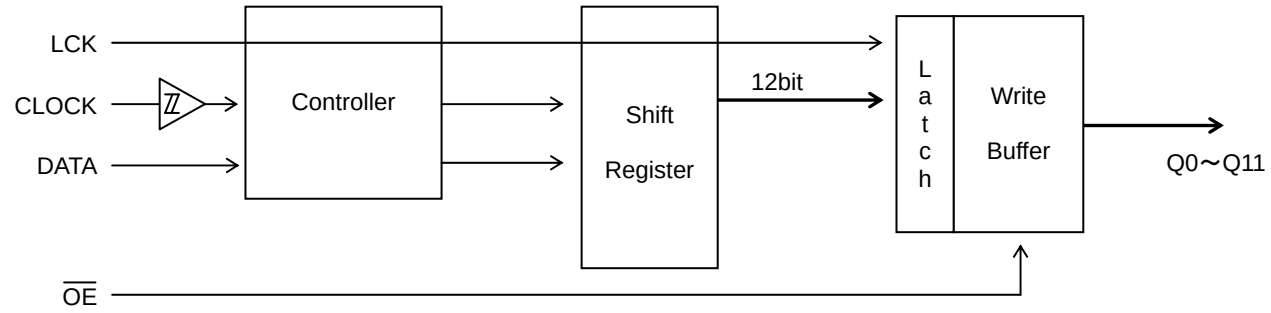
Parameter	Symbol	Min.	Typ.	Max.	Unit	Condition
Power Supply Voltage	VDD	2.7	-	5.5	V	
Input high-level Voltage	VIH	2.0	-	-	V	VDD=5V
Input low-level Voltage	VIL	-	-	0.6	V	VDD=5V
Output high-level Voltage	VOH	VDD-1.5	-	-	V	IOH=-25mA
		VDD-1.0	-	-		IOH=-15mA
		VDD-0.5	-	-		IOH=-10mA
Output low-level Voltage	VOL	-	-	1.5	V	IOL=25mA
		-	-	1.0		IOL=15mA
		-	-	0.8		IOL=10mA
Quiescent Current	IDDST	-	-	5	μA	VIL=VSS, VIH=VDD
Input high-level Current	IIH	-	-	1	μA	
Input low-level Current	IIL	-	-	1	μA	

●Block diagram

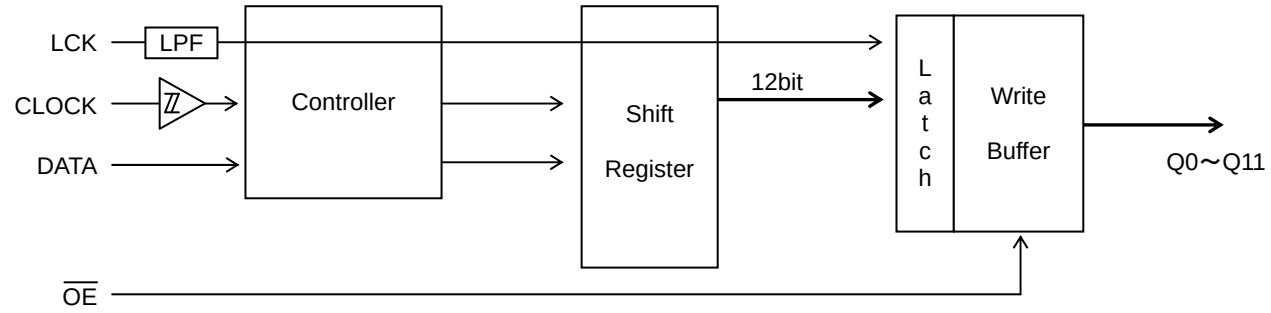
BU2050F



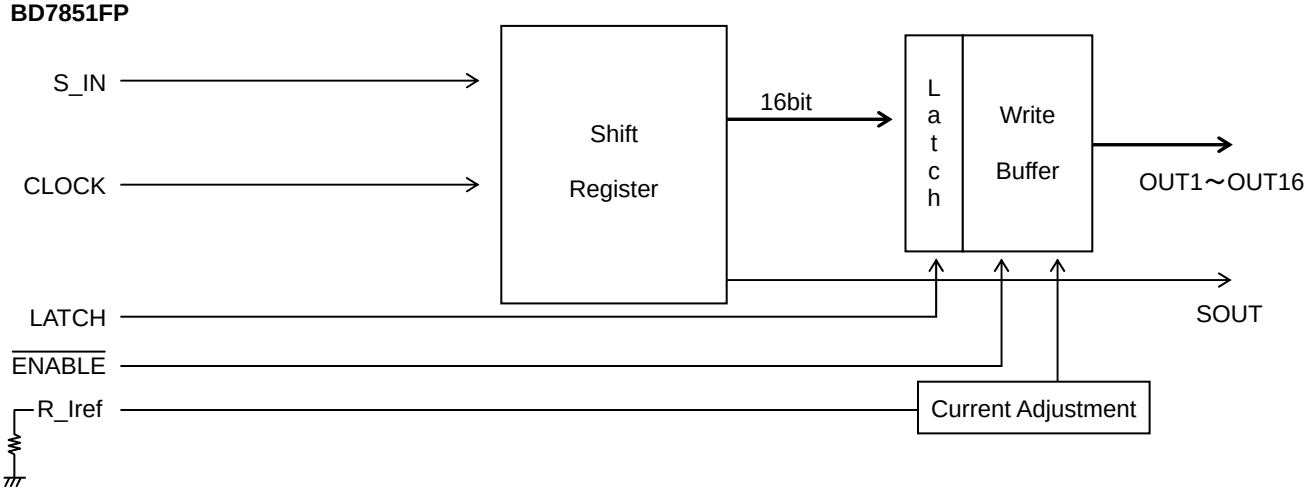
BU2092F/BU2092FV



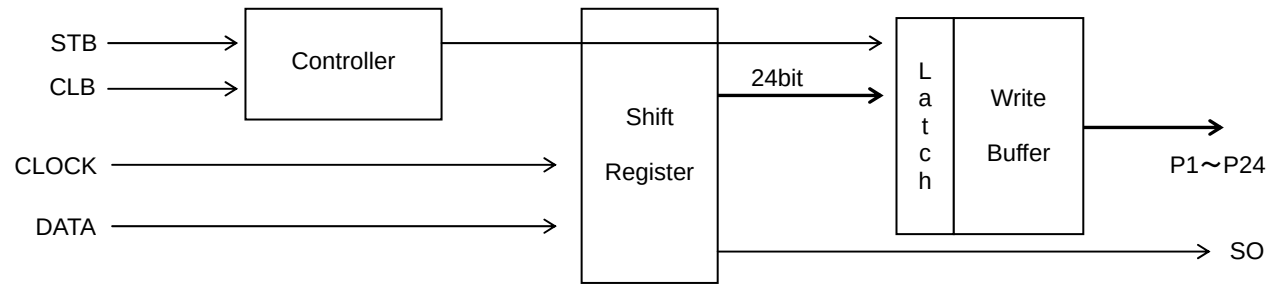
BU2099FV



BD7851FP



BU2152FS



●Operating description

(1) Data clear

When the reset terminal ($\overline{CLR}$, CLB) is set to “L”, the content of all latch circuits are set to “H”, and all parallel outputs are initialised. (For model with reset terminal only)

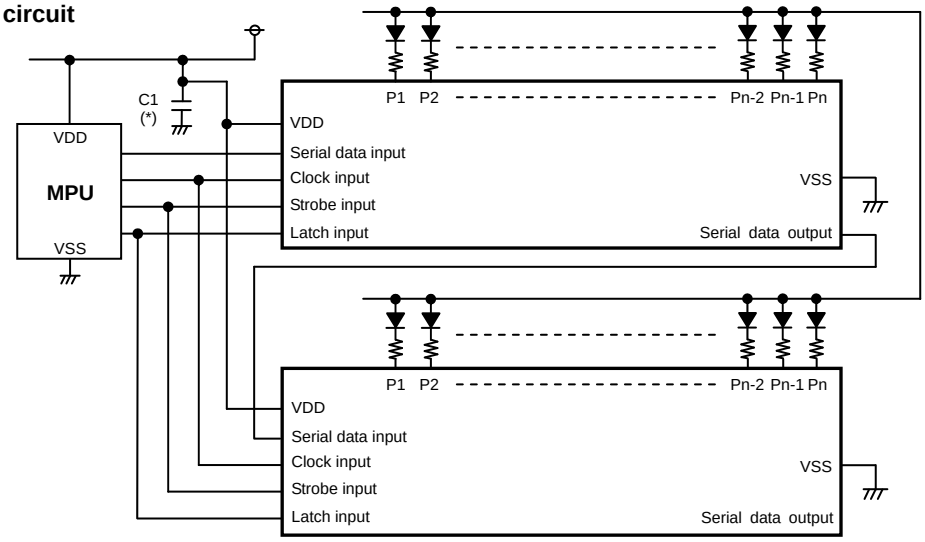
(2) Data transfer

Serial data is sequentially input to the shift register during the rise of the clock time (strobe signal is not active). When the strobe signal is active, the content of the shift register are transferred to the latch circuit.

(3) Cascade connection

Serial input data is output from the serial output through the shift register, regardless of the strobe signal. (except for BU2050F, BU2092F/BU2092FV)

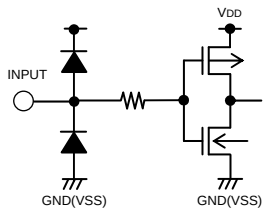
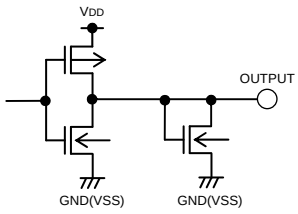
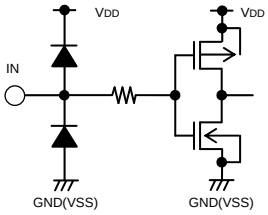
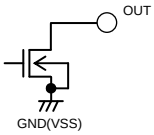
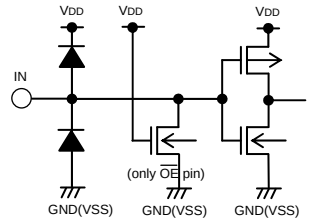
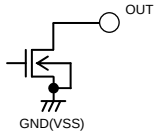
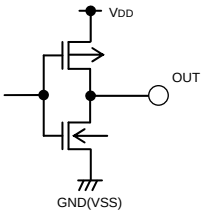
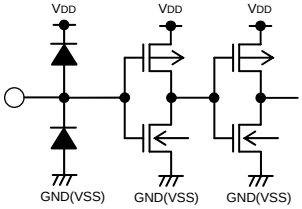
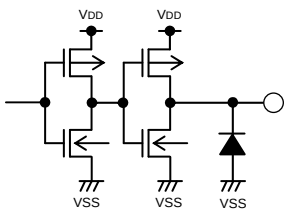
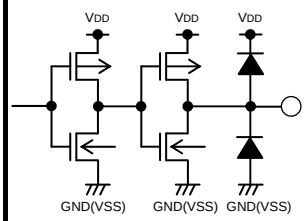
●Application circuit



(*C1 must be placed as close to the terminal as possible.)

Fig. 1

●Interfaces

BU2050F	BU2050F	BU2092F/BU2092FV	BU2092F/BU2092FV
DATA, CLOCK, $\overline{STB}$, $\overline{CLR}$	P1～P8	DATA, CLOCK, LCK, $\overline{OE}$	Q0～Q11
			
BU2099FV	**BU2099FV**	**BU2099FV**	**BU2152FS**
DATA, CLOCK, LCK, $\overline{OE}$	Q0～Q11	SO	CLOCK, DATA, STB, CLB
			
BU2152FS	**BU2152FS**		
P1～P28	SO		
			

【BU2050F】

●Pin descriptions

Pin No.	Pin Name	Function
1	P3	Parallel Data Output
2	P4	
3	P5	
4	VSS	GND
5	P6	Parallel Data Output
6	P7	
7	P8	
8	DATA	Serial Data Input
9	CLK	Clock Signal Input
10	$\overline{STB}$	Strobe Signal Input In case of “L”, the data of shift register outputs. In case of “H”, all parallel outputs and data of latch circuit do not change.
11	$\overline{CLR}$	Reset Signal Input In case of “L”, the data of latch circuit reset, and all parallel output (P1～P8) can be L. Normally $\overline{CLR}$=H
12	P1	Parallel Data output
13	P2	
14	VDD	Power Supply

●Timing chart

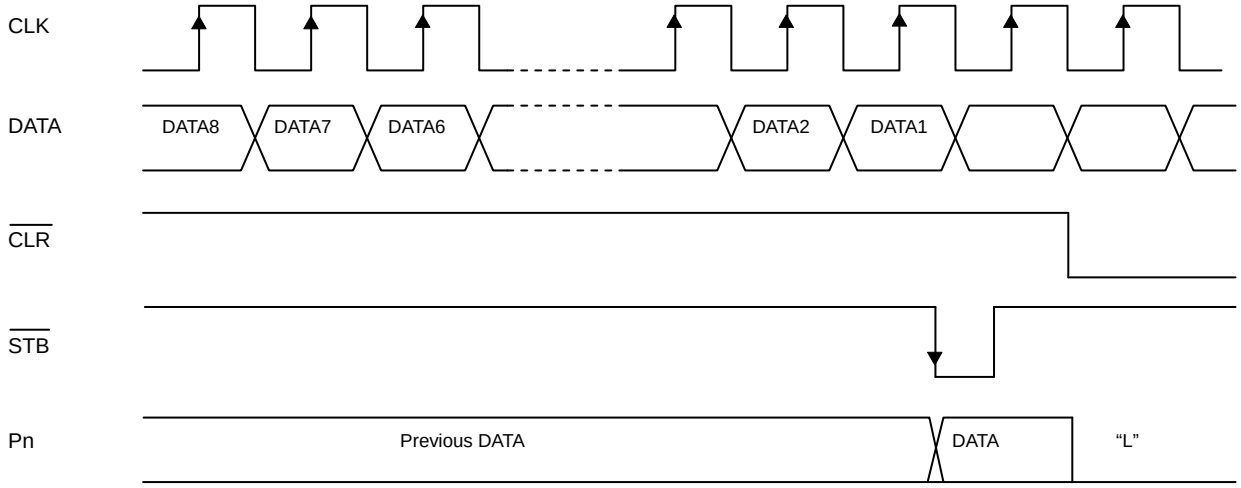


Fig. 2

1. After the power is turned on and the voltage is stabilized, STB should be activated, after clocking 8 data bits into the DATA pin.
2. Pn parallel output data of the shift register is set after the 8th clock by the STB.
3. Since the STB is level latch, data is retained in the “L” section and renewed in the “H” section of the STB.

［Function explanation］

- A latch circuit has the reset function, which is common in all bits. In case of $\overline{CLR}$ terminal is “L”, the latch circuit is reset non-synchronously without the other input condition, and all parallel output can be “L”.
- A serial data inputted from DATA terminal is read in shift register with synchronized rising of clock.
  In case of $\overline{STB}$ is “L” ($\overline{CLR}$ is ”H”), transmit the data which read in the shift register to latch circuit, and outputs from the parallel data output terminal (P1～P8).
  In case of $\overline{STB}$ is “H”, all parallel outputs and the data of latch do not change.

●**Switching characteristics (Unless otherwise specified, V_{DD}=4.5 to 5.5V, Ta=25℃)**

Parameter	Symbol	Limit			Unit	Condition
		Min.	Typ.	Max.		
Set up time (DATA-CLK)	t_{SD}	20	-	-	ns	-
Hold time (DATA-CLK)	t_{HD}	20	-	-	ns	-
Set up time ($\overline{STB}$ – CLK)	t_{SSTB}	30	-	-	ns	-
Hold time ($\overline{STB}$ – CLK)	t_{HSTB}	30	-	-	ns	-
Propagation ($\overline{CLR}$ – P1～P8)	t_{PDPCK}	-	-	100	ns	P1～P8 terminal load 20pF or less
Propagation ($\overline{STB}$ – P1～P8)	t_{PDPSTB}	-	-	80	ns	P1～P8 terminal load 20pF or less
Propagation ($\overline{CLR}$ – P1～P8)	t_{PDPCLR}	-	-	80	ns	P1～P8 terminal load 20pF or less
Maximum clock frequency	f_{MAX}	5	-	-	MHz	-

●**Switching Time Test Waveform**

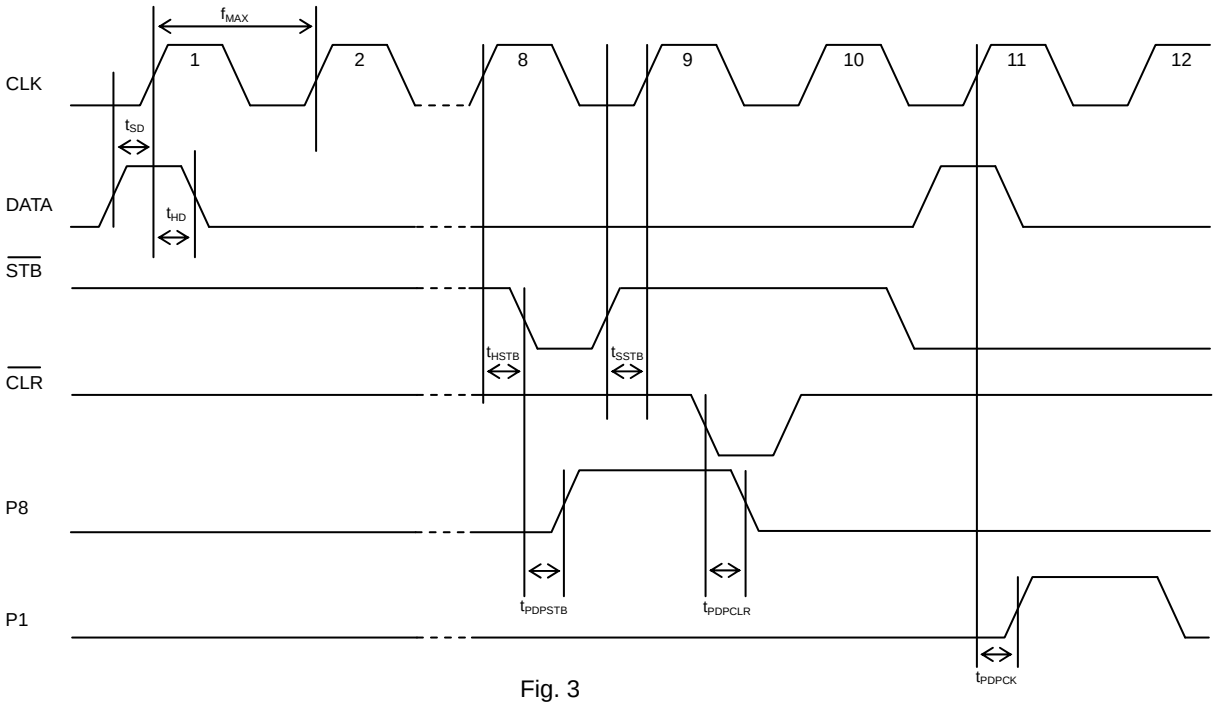


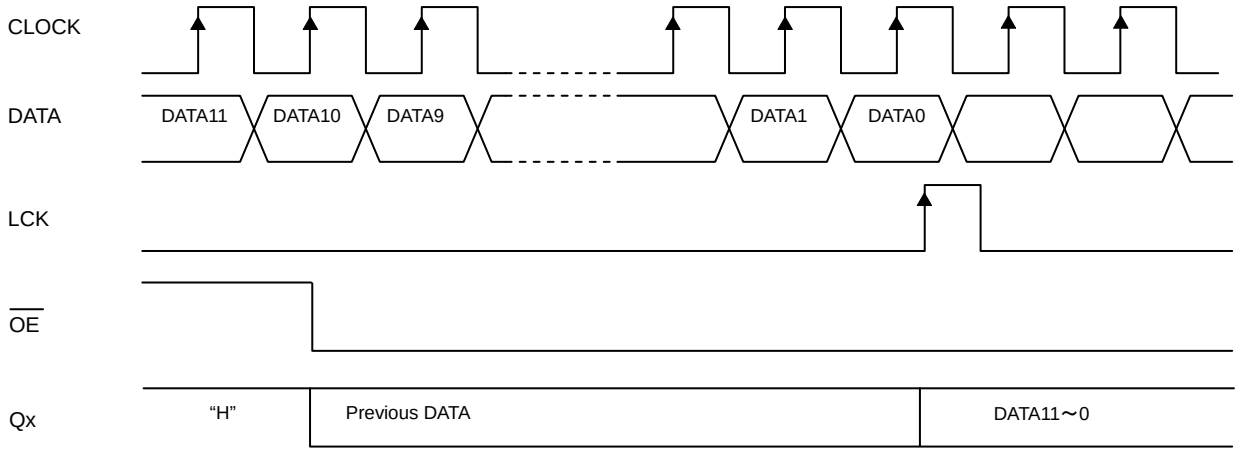
Fig. 3

【BU2092F/BU2092FV】

●Pin descriptions

Pin No.	Pin Name	I/O	Function
1	V_{SS}	-	GND
2	DATA	I	Serial Data Input
3	CLOCK	I	Shift clock of DATA (Rising Edge Trigger)
4	LCK	I	Latch clock of DATA (Rising Edge Trigger)
5～11, 14～18	Q0～Q11	O	Parallel Data Output (Nch Open Drain FET) Latch Data: L / H Output FET: ON / OFF
12, 13	N.C.	-	Non connected
17	$\overline{OE}$	I	Output Enable (“H” level : output FET is OFF)
18	V_{DD}	-	Power Supply

●Timing chart



Note) Diagram shows a status where a pull-up resistor is connected to output.

Fig. 4

1. After the power is turned on and the voltage is stabilized, LCK should be activated, after clocking 12 data bits into the DATA terminal.
2. Qx parallel output data of the shift register is set after the 12th clock by the LCK.
3. Since the LCK is a label latch, data is retained in the “L” section and renewed in the “H” section of the LCK.
4. Data retained in the internal latch circuit is output when the $\overline{OE}$ is in the “L” section.

［Truth Table］

Input				Function
CLOCK	DATA	LCK	$\overline{OE}$	
×	×	×	H	Output (Q0～Q11) Disable
×	×	×	L	Output (Q0～Q11) Enable
↑	L	×	×	Store “L” in the first stage data of shift register, the previous stage data in the others. (The conditions of storage register and output have no change.)
↑	H	×	×	Store “H” in the first stage data of shift register, the previous stage data in the others. (The conditions of storage register and output have no change.)
↓	×	×	×	The data of shift register has no change.
×	×	↑	×	The data of shift register is transferred to the storage register.
×	×	↓	×	The data of storage register has no change.

●**Switching characteristics (Unless otherwise specified, V_{DD}=5V, V_{SS}=0V, Ta=25℃)**

Parameter	Symbol	Limit			Unit	V_{DD}(V)	Condition
		Min.	Typ.	Max.			
Minimum Clock Pulse Width	t_W	1000	-	-	ns	3	-
		500	-	-	ns	5	
Minimum Latch Pulse Width (LCK)	t_W (LCK)	1000	-	-	ns	3	-
		500	-	-	ns	5	
Setup Time (LCK→CLOCK)	t_S	400	-	-	ns	3	-
		200	-	-	ns	5	
Setup Time (DATA→CLOCK)	t_{SU}	400	-	-	ns	3	-
		200	-	-	ns	5	
Hold Time (CLOCK→DATA)	t_H	400	-	-	ns	3	-
		200	-	-	ns	5	
Propagation (LCK→OUTPUT QX)	t_{PLZ} (LCK)	-	90	-	ns	3	R_L=5kΩ
		-	55	-	ns	5	C_L=10pF
	t_{PZL} (LCK)	-	115	-	ns	3	R_L=5kΩ
		-	50	-	ns	5	C_L=10pF
Propagation ($\overline{OE}$ →OUTPUT QX)	t_{PLZ}	-	70	-	ns	3	R_L=5kΩ
		-	45	-	ns	5	C_L=10pF
	t_{PZL}	-	80	-	ns	3	R_L=5kΩ
		-	35	-	ns	5	C_L=10pF

●**Switching Time Test Circuit**

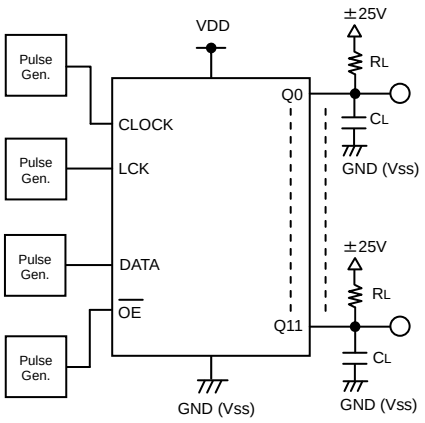


Fig. 5

【BU2092F/BU2092FV】

●Switching Time Test Waveforms

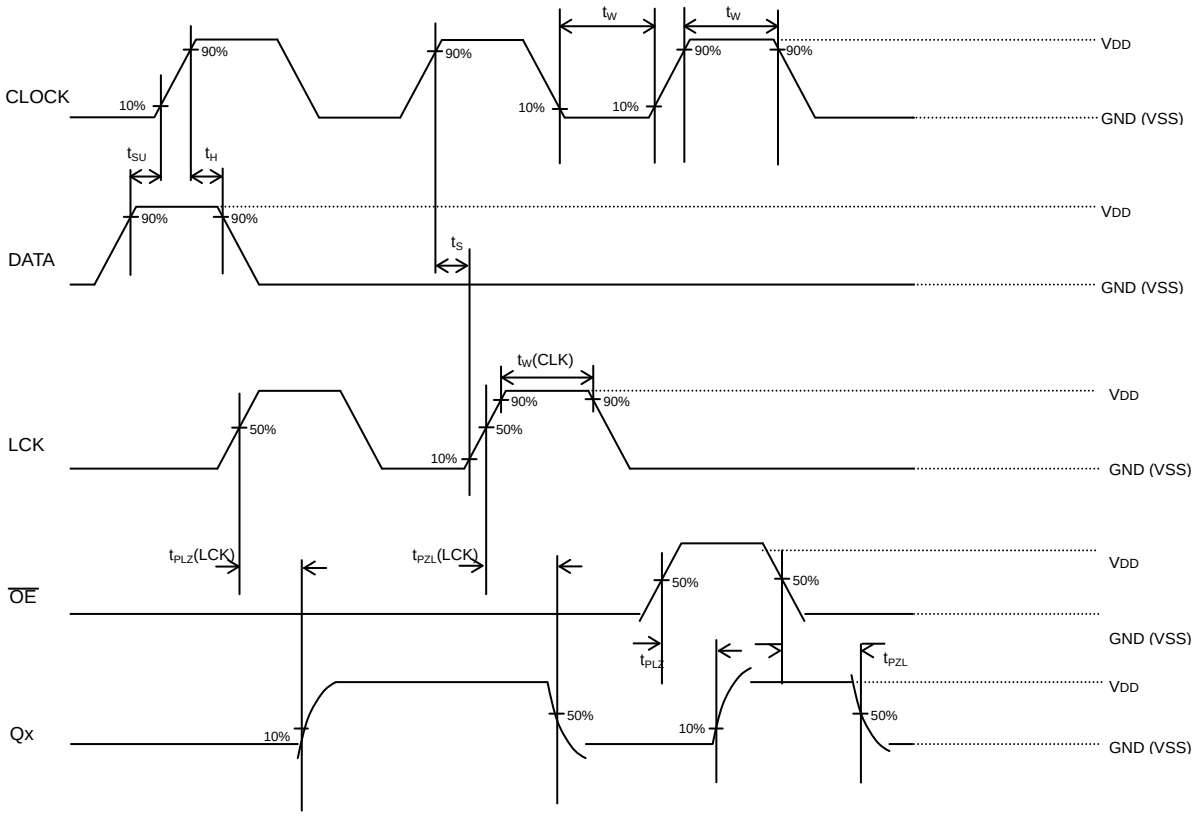


Fig. 6

【BU2099FV】

●Pin descriptions

Pin No.	Pin Name	I/O	Function
1	V_{SS}	-	GND
2	N.C.	-	Non connected
3	DATA	I	Serial Data Input
4	CLOCK	I	Shift clock of Shift register (Rising Edge Trigger)
5	LCK	I	Latch clock of Storage register (Rising Edge Trigger)
6～17	Q0～Q11 (Qx)	O	Parallel Data Output (Nch Open Drain FET) Latch Data: L / H Output FET: ON / OFF
18	SO	O	Serial Data Output
19	$\overline{OE}$	I	Output Enable Control Input ＊$\overline{OE}$ pin is pulled down to Vss.
20	V_{DD}	-	Power Supply

●Timing chart

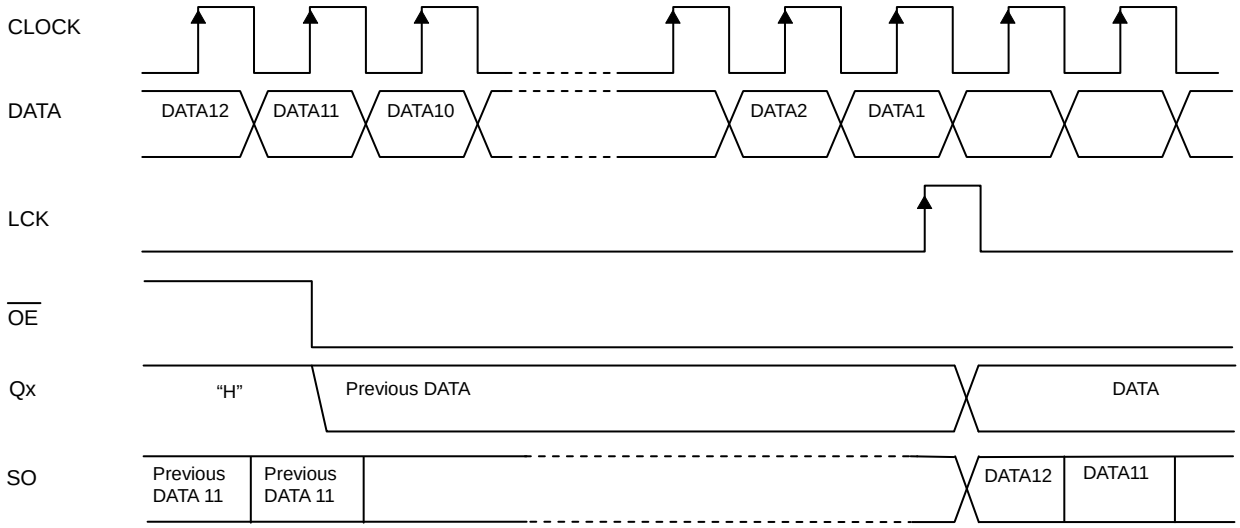


Fig. 7

1. After the power is turned on and the voltage is stabilized, LCK should be activates, after clocking 12 data bits into the DATA terminal.
2. Qx parallel output data of the shift register is set after the 12th clock by the LCK.
3. Since the LCK is a label latch, data is retained in the "L" section and renewed in the "H" section of the LCK.
4. Data retained in the internal latch circuit is output when the $\overline{OE}$ is in the "L" section.
5. The final stage data of the shift register is output to the SO by synchronizing with the rise time of the CLOCK.

［Truth Table］

Input				Function
CLOCK	DATA	LCK	$\overline{OE}$	
×	×	×	H	All the output data output "H" with pull-up.
×	×	×	L	The Q0～Q11 output can be enable and output the data of storage register.
↑	L	×	×	Store "L" in the first stage data of shift register, the previous stage data in the others. (The conditions of storage register and output have no change.)
↑	H	×	×	Store "H" in the first stage data of shift register, the previous stage data in the others. (The conditions of storage register and output have no change.)
↓	×	×	×	The data of shift register has no change. SO outputs the final stage data of shift register with synchronized falling edge of CLOCK, not controlled by $\overline{OE}$.
×	×	↑	×	The data of shift register is transferred to the storage register.
×	×	↓	×	The data of storage register has no change.

＊The Q0～Q11 output have a Nch open drain Tr. The Tr is ON when data from shift register is "L", and Tr is OFF when data is "H".

【BU2099FV】

●**Switching characteristics (Unless otherwise specified, V_{DD}=5V, V_{SS}=0V, Ta=25℃)**

Parameter	Symbol	Limit			Unit		Condition
		Min.	Typ.	Max.		V_{DD}(V)	
Minimum Clock Pulse Width (CLOCK)	t_W	1000	-	-	ns	3	-
		500	-	-	ns	5	
Minimum Latch Pulse Width (LCK)	t_W (LCK)	1000	-	-	ns	3	-
		500	-	-	ns	5	
Setup Time (LCK→CLOCK)	t_S	400	-	-	ns	3	-
		200	-	-	ns	5	
Setup Time (DATA→CLOCK)	t_{su}	400	-	-	ns	3	-
		200	-	-	ns	5	
Hole Time (CLOCK→DATA)	t_H	400	-	-	ns	3	-
		200	-	-	ns	5	
Propagation (SO)	t_{PLH}	-	-	500	ns	3	-
	t_{PHL}	-	-	250	ns	5	-
Propagation (LCK→QX) *	t_{PLZ} (LCK)	-	360	-	ns	3	R_L=5kΩ
		-	170	-	ns	5	C_L=10pF
	t_{PZL} (LCK)	-	260	-	ns	3	R_L=5kΩ
		-	175	-	ns	5	C_L=10pF
Propagation (QE →QX) *	t_{PLZ}	-	115	-	ns	3	R_L=5kΩ
		-	85	-	ns	5	C_L=10pF
	t_{PZL}	-	175	-	ns	3	R_L=5kΩ
		-	65	-	ns	5	C_L=10pF
Noise Pulse Suppression Time (LCK) *	t_I	-	30		ns	-	-
		-	20		ns	-	

*Reference value

●**Input Voltage Test Circuit**

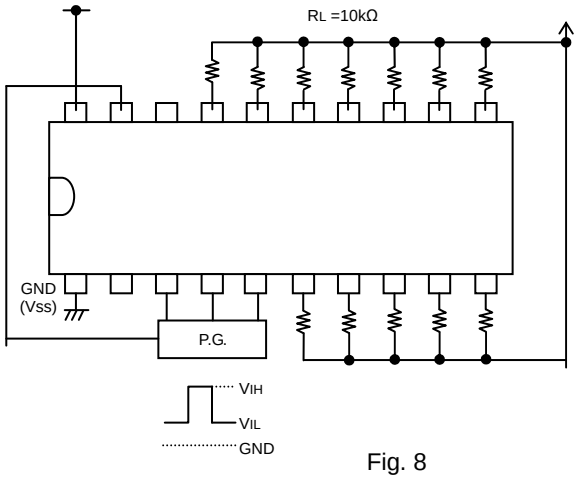


Fig. 8

●**Switching Time Test Circuit**

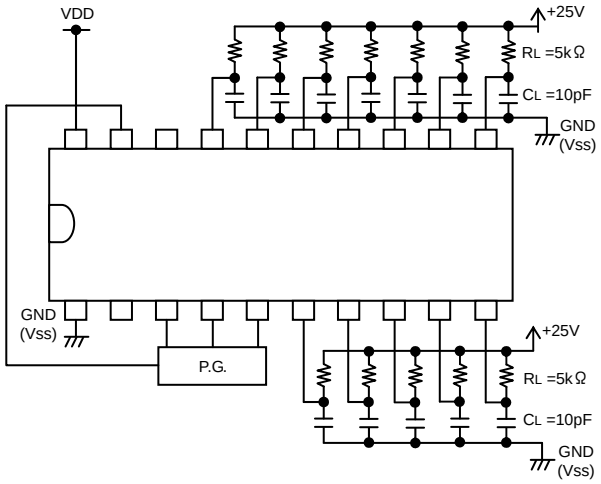
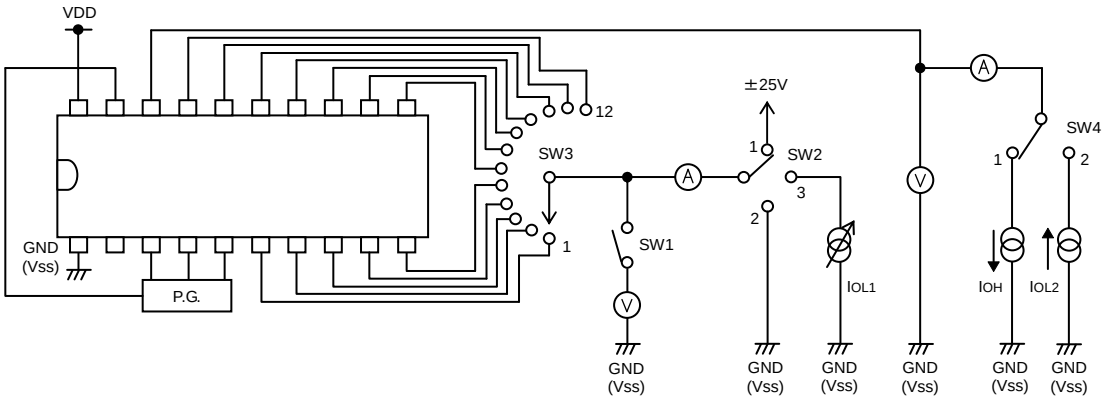


Fig. 9

【BU2099FV】

●Output Voltage Test Circuit



Test condition

VOL1 : Set all data “L”. SW1=”ON”, SW2=”3”, SW3=”1”～”12”.

VOL2 : Set output data “L” to SO and SW4 is positioned to “2”, then voltage is measured at IOL2.

VOH : Set output data “H” to SO and SW4 is positioned to “1”, then voltage is measured at IOH.

Fig. 10

●Switching Time Test Waveforms

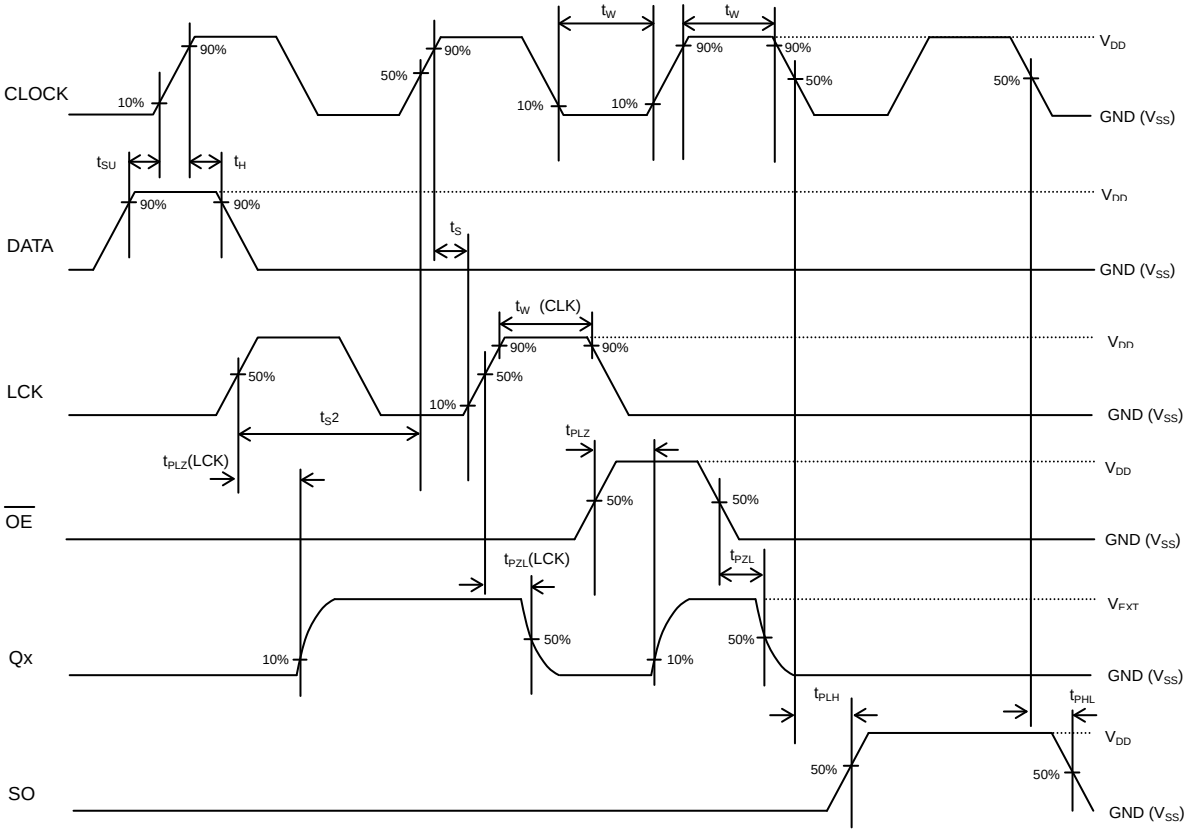


Fig. 11

【BD7851FP】

●Pin descriptions

Pin No.	Pin Name	Function
1	GND	Ground
2	R_Iref	Reference Current Output Current setting
3	LATCH	Latch Signal Input
4	S_IN	Serial Data Input
5～15	OUT16 ～OUT6	Reference Current Output
16	P_GND	Ground for Driver
17～21	OUT5 ～OUT1	Reference Current Output
22	SOUT	Serial Data Output
23	CLOCK	Clock Input
24	$\overline{\text{ENABLE}}$	$\overline{\text{ENABLE}}$
25	V_{CC}	V_{CC}

●Timing chart

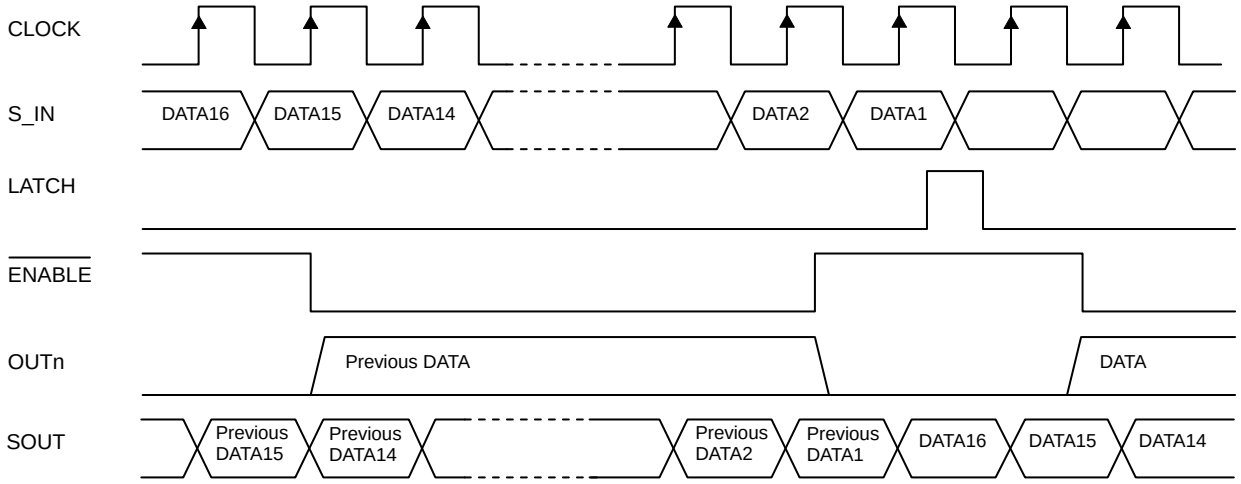


Fig. 12

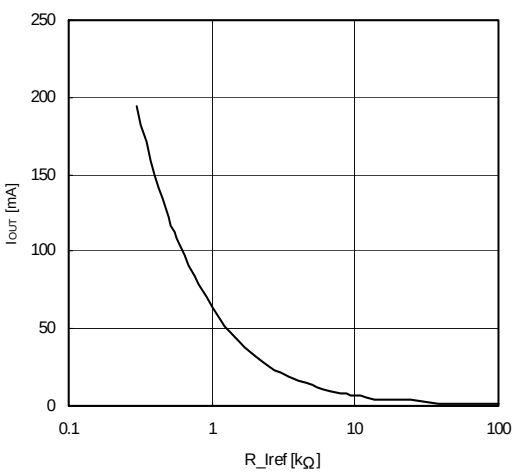
1. After the power is turned on and the voltage is stabilized, LATCH should be activated, after clocking 16 data bits into the S_IN terminal.
2. OUTn parallel output data of the shift register is set after the 16th clock by the LATCH.
3. The final stage data of the shift register is outputted to the SOUT by synchronizing with the rise time of the CLOCK.
4. Since the LATCH is a label latch, data is retained in the “L” section and renewed in the “H” section of the LATCH.
5. Data retained in the internal latch circuit is outputted when the $\overline{\text{ENABLE}}$ is in the “L” section. When the $\overline{\text{ENABLE}}$ is in the “H” section, data is fixed in the “H” section.

【BD7851FP】

●Timing characteristics (Unless otherwise specified, Vcc=5V, Ta=25℃)

Parameter	Symbol	Limit			Unit	Condition
		Min.	Typ.	Max.		
Frequency CLOCK	fclk	-	-	10	MHz	
Pulse Width CLOCK	t_{wh}	20	50	-	ns	CLOCK
Pulse Width LATCH	t_{wh}	40	50	-	ns	LATCH
Pulse Width $\overline{\text{ENABLE}}$	t_w	30	-	-	ns	$\overline{\text{ENABLE}}$
Rise Time / Fall Time	t_r / t_f	-	30	100	ns	CLOCK
Setup Time	t_{SU}	30	50	-	ns	S_IN-CLOCK
		30	50	-		LATCH-CLOCK
Hold Time	t_h	30	50	-	ns	S_IN-CLOCK
		30	50	-		LATCH-CLOCK
Rise Time	t_r	-	300	-	ns	OUTn
		-	-	50		SOUT
Fall Time	t_f	-	300	-	ns	OUTn
		-	-	50		SOUT
Propagation	t_{pLH}	-	400	650	ns	CLK-SOUT, LATCH $\overline{\text{ENABLE}}$-OUTn
	t_{pHL}	-	300	400		CLK-SOUT, LATCH $\overline{\text{ENABLE}}$-OUTn

●Reference Current of Output Current



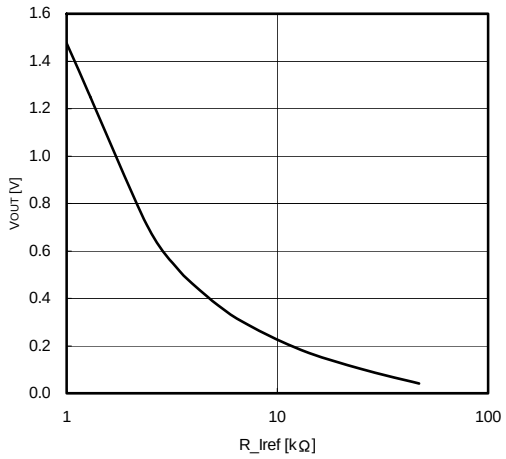
[Condition]
Vcc=5.0V, Vo=5.0V, Ta=25℃

The reference current of output current is determined by the external resistor.
(between 2pin and GND)

∗ This is a data for the standard sample, not guaranteed the characteristic.

Fig. 13

●R_Iref-VOUT



[Condition]
Vcc=5.0V, Ta=27℃, all bit : ON

∗ Notes the increase of consumption current Icc, in case sets the voltage of VOUT lower. See the graph above.

Fig. 14

【BD7851FP】

●Test Circuit 1

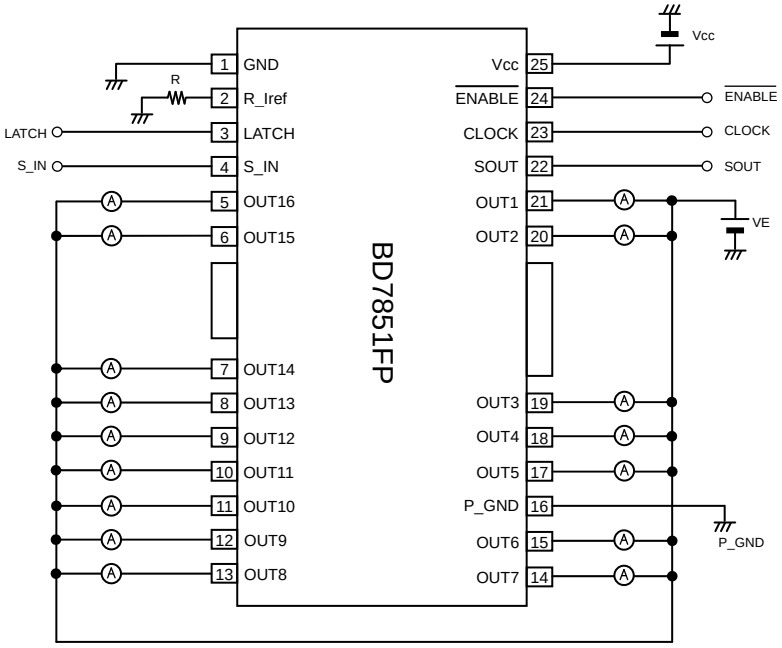
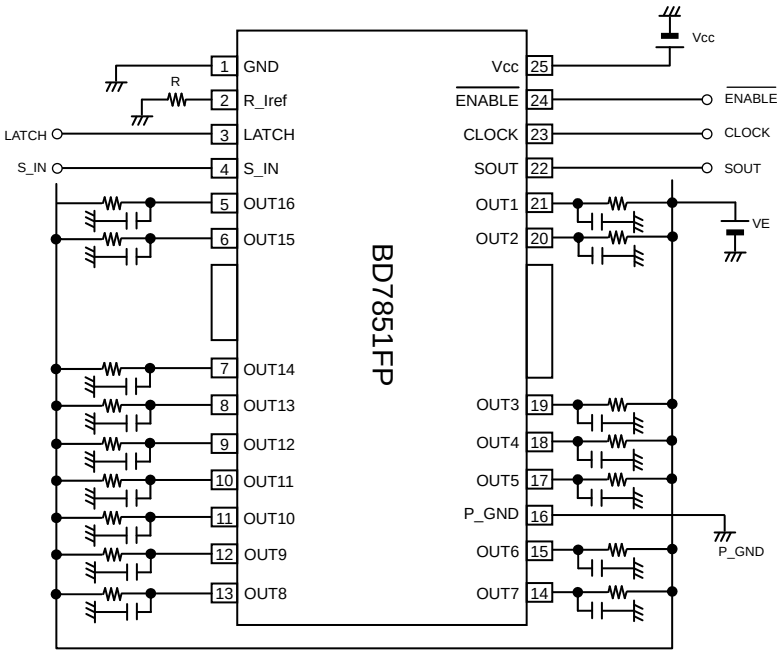


Fig. 15

●Test Circuit 2



∗ R=51Ω (note : R_Iref=1.3kΩ) , C=15pF

Fig. 16

【BD7851FP】

●Switching Time Test Waveforms

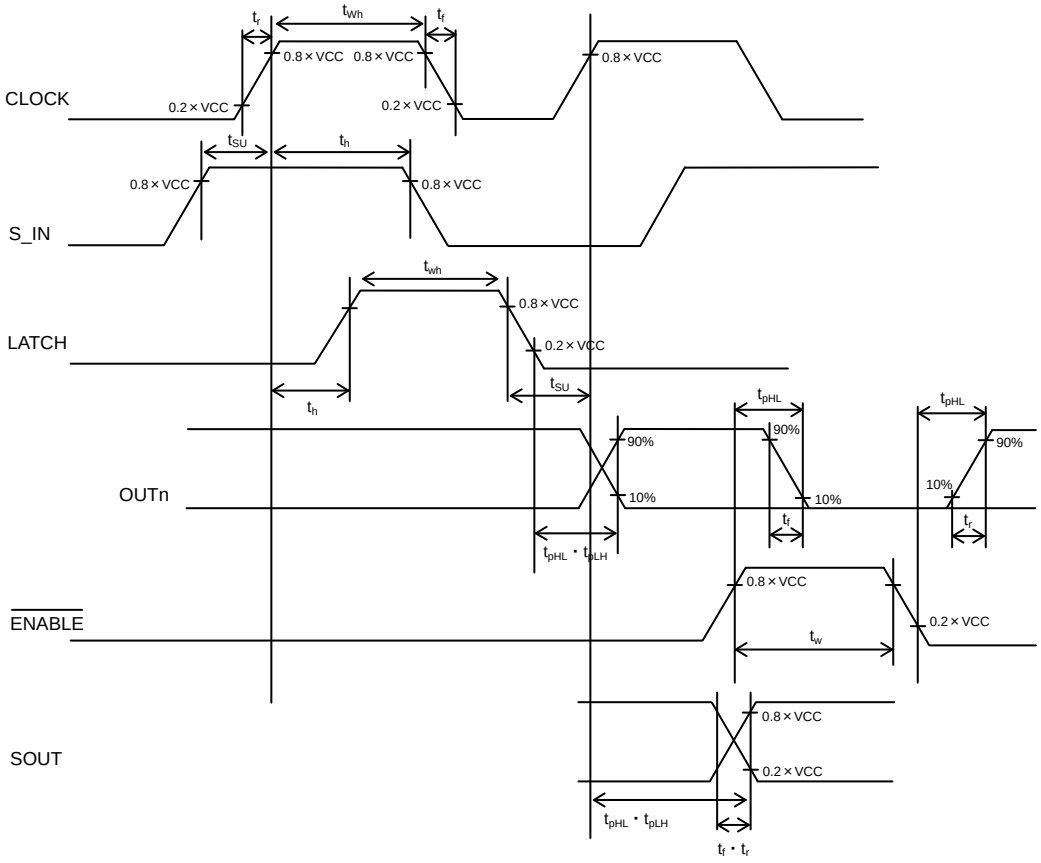


Fig. 17

【BU2152FS】

●Pin descriptions

Pin No.	Pin Name	I/O	Function
1	V_{SS}	-	Ground
2	CLK	I	Clock Input
3	V_{SS}	-	Ground
4	DATA	I	Serial Data Input
5～28	P1～P24	O	Parallel Data Output
29	SO	O	Cascade Output
30	STB	I	Strobe Signal Input active “L”
31	CLB	I	Clear Signal Input active “L”
32	V_{DD}	-	Power Supply

●Timing chart

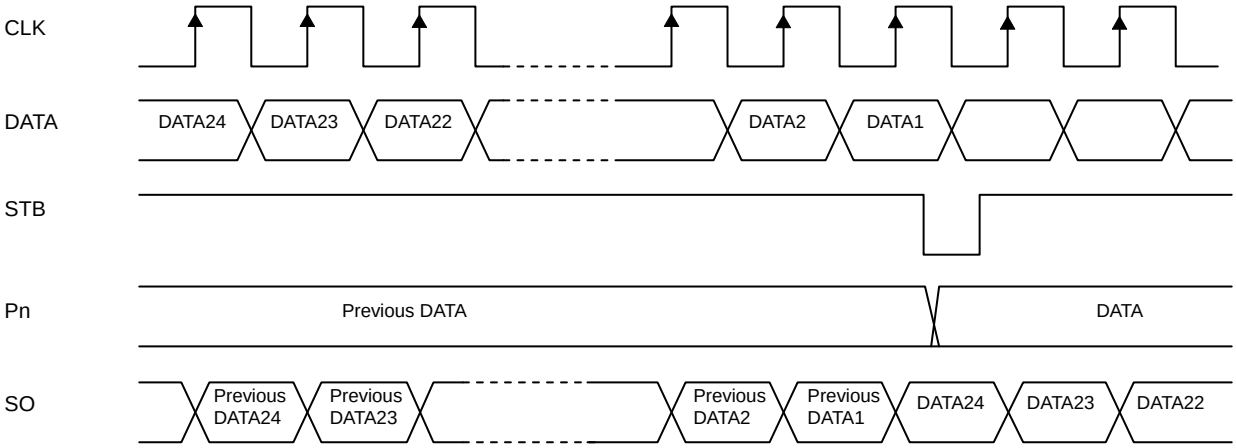


Fig. 18

1. After the power is turned on and the voltage is stabilized, STB should be activated, after clocking 24 data bits into the DATA terminal.
2. Pn parallel output data of the shift register is set after the 24th clock by the LCK.
3. Since the STB is a label latch, data is retained in the “H” section and renewed in the “L” section of the STB.
4. The final stage data of the shift register is outputted to the SO by synchronizing with the rise time of the CLOCK.

［Truth Table］

Input			Function
CLK	STB	CLB	
×	×	L	All the data of the latch circuit are set to “H” (data of shift register does not change), all the parallel outputs are “H”.
↑	H	H	Serial data of DATA pin are latched to the shift register. At this time, the data of the latch circuit does not change.
L	L	H	The data of the shift register are transferred to the latch circuit, and the data of the latch circuit are outputted from the parallel output pin.
H			
↑			The data of the shift register shifts 1bit, and the data of the latch circuit and parallel output also change.

【BU2152FS】

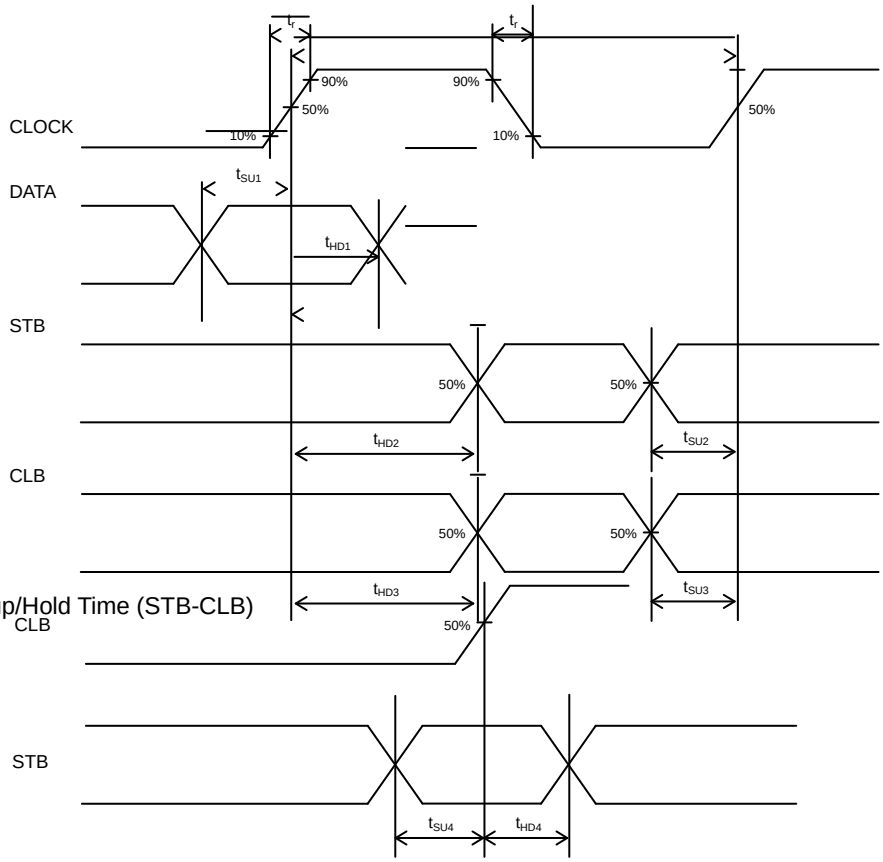
●Switching characteristics (Unless otherwise specified, V_{DD}=2.7 to 5.5V, V_{SS}=0V, Ta=25℃)

Parameter	Symbol	Limit			Unit	Condition
		Min.	Typ.	Max.		
Maximum Clock Frequency	f_{MAX}	5	-	-	MHz	
Setup Time 1	t_{SU1}	20	-	-	ns	DATA-CLK
Hold Time 1	t_{HD1}	20	-	-	ns	CLK-DATA
Setup Time 2	t_{SU2}	30	-	-	ns	STB-CLK
Hold Time 2	t_{HD2}	30	-	-	ns	CLK-STB
Setup Time 3	t_{SU3}	30	-	-	ns	CLB-CLK
Hold Time 3	t_{HD3}	30	-	-	ns	CLK-CLB
Setup Time 4	t_{SU4}	30	-	-	ns	STB-CLB
Hold Time 4	t_{HD4}	30	-	-	ns	CLB-STB
Output Delay Time 1*	t_{PD1}	-	-	100	ns	CLK-P1～P24
Output Delay Time 2*	t_{PD2}	-	-	80	ns	STB-P1～P24
Output Delay Time 3*	$t_{PD3.}$	-	-	80	ns	CLB-P1～P24

*50pF of load is attached.

●Switching characteristic conditions

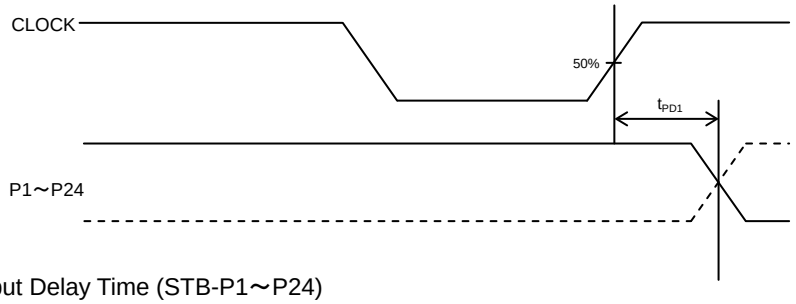
○Setup/Hold Time (DATA-CLOCK, STB-CLOCK, CLB-CLOCK)



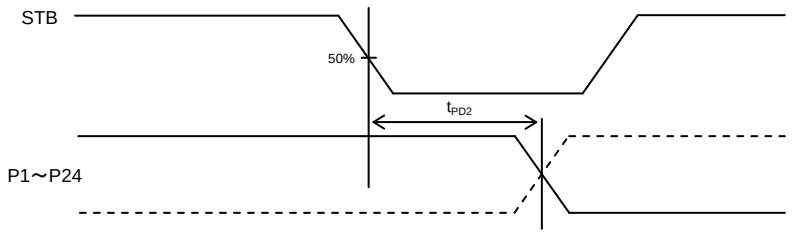
○Setup/Hold Time (STB-CLB)

Fig. 19 Switching characteristic conditions 1

○Output Delay Time (CLOCK-P1～P24)



○Output Delay Time (STB-P1～P24)



○ Output Delay Time (CLB-P1～P24)

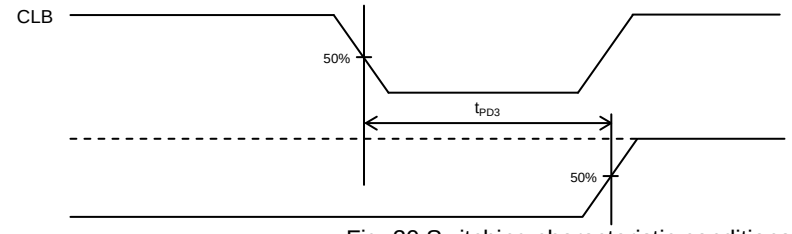


Fig. 20 Switching characteristic conditions 2

●Notes for use

1. Absolute maximum ratings
   An excess in the absolute maximum ratings, such as supply voltage, temperature range of operating conditions, etc., can break down the devices, thus making impossible to identify breaking mode, such as a short circuit or an open circuit. If any over rated values will expect to exceed the absolute maximum ratings, consider adding circuit protection devices, such as fuses.

2. Connecting the power supply connector backward
   Connecting of the power supply in reverse polarity can damage IC. Take precautions when connecting the power supply lines. An external direction diode can be added.

3. Power supply lines
   Design PCB layout pattern to provide low impedance GND and supply lines. To obtain a low noise ground and supply line, separate the ground section and supply lines of the digital and analog blocks. Furthermore, for all power supply terminals to ICs, connect a capacitor between the power supply and the GND terminal. When applying electrolytic capacitors in the circuit, not that capacitance characteristic values are reduced at low temperatures.

4. GND voltage
   The potential of GND pin must be minimum potential in all operating conditions.

5. Thermal design
   Use a thermal design that allows for a sufficient margin in light of the power dissipation (Pd) in actual operating conditions.

6. Inter-pin shorts and mounting errors
   Use caution when positioning the IC for mounting on printed circuit boards. The IC may be damaged if there is any connection error or if pins are shorted together.

7. Actions in strong electromagnetic field
   Use caution when using the IC in the presence of a strong electromagnetic field as doing so may cause the IC to malfunction.

8. Testing on application boards
   When testing the IC on an application board, connecting a capacitor to a pin with low impedance subjects the IC to stress. Always discharge capacitors after each process or step. Always turn the IC's power supply off before connecting it to or removing it from a jig or fixture during the inspection process. Ground the IC during assembly steps as an antistatic measure. Use similar precaution when transporting or storing the IC.

9. Ground Wiring Pattern
   When using both small signal and large current GND patterns, it is recommended to isolate the two ground patterns, placing a single ground point at the ground potential of application so that the pattern wiring resistance and voltage variations caused by large currents do not cause variations in the small signal ground voltage. Be careful not to change the GND wiring pattern of any external components, either.

10. Unused input terminals
    Connect all unused input terminals to VDD or VSS in order to prevent excessive current or oscillation.
    Insertion of a resistor (100kΩ approx.) is also recommended.

●Ordering part number

B	U	2	0	9	2	F	V	-	E	2

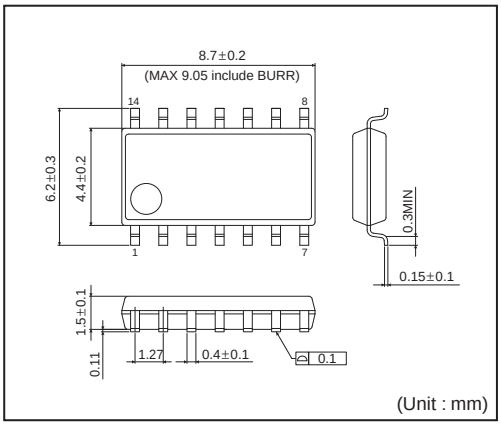
Part No.

Part No.
2050
2092
2099
7851
2152

Package
F : SOP14
: SOP18
FV : SSOP-B20
FP : HSOP25
FS : SSOP-A32

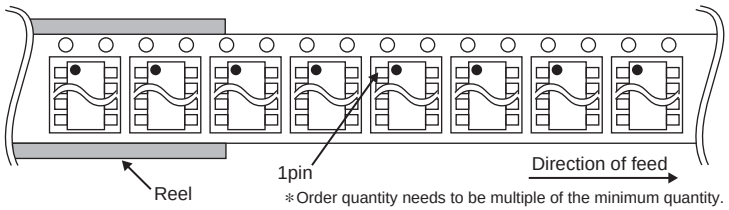
Packaging and forming specification
E2: Embossed tape and reel

SOP14



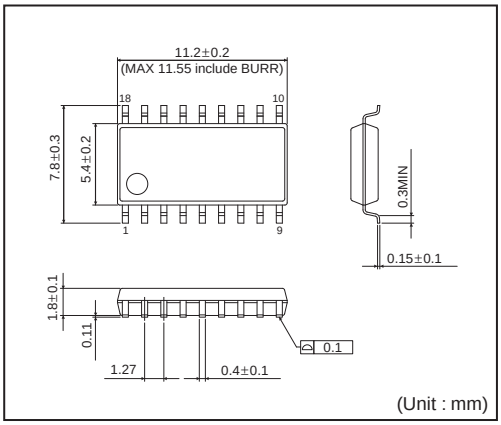
<Tape and Reel information>

Tape	Embossed carrier tape
Quantity	2500pcs
Direction of feed	E2 (The direction is the 1pin of product is at the upper left when you hold reel on the left hand and you pull out the tape on the right hand)



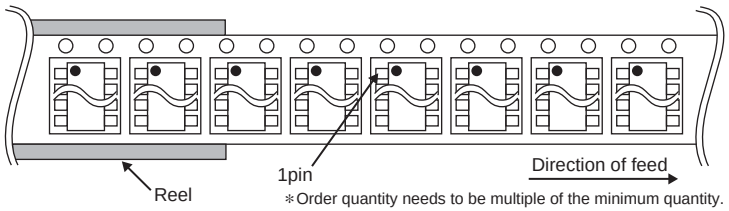
∗Order quantity needs to be multiple of the minimum quantity.

SOP18



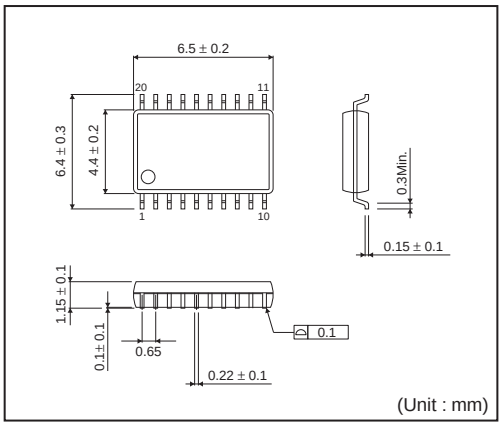
<Tape and Reel information>

Tape	Embossed carrier tape
Quantity	2000pcs
Direction of feed	E2 (The direction is the 1pin of product is at the upper left when you hold reel on the left hand and you pull out the tape on the right hand)



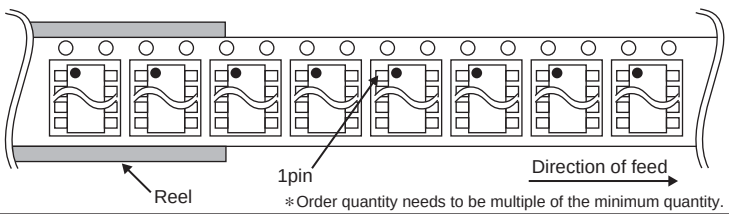
∗Order quantity needs to be multiple of the minimum quantity.

SSOP-B20



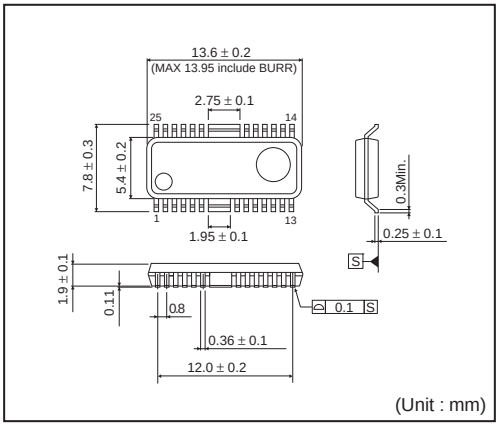
<Tape and Reel information>

Tape	Embossed carrier tape
Quantity	2500pcs
Direction of feed	E2 (The direction is the 1pin of product is at the upper left when you hold reel on the left hand and you pull out the tape on the right hand)



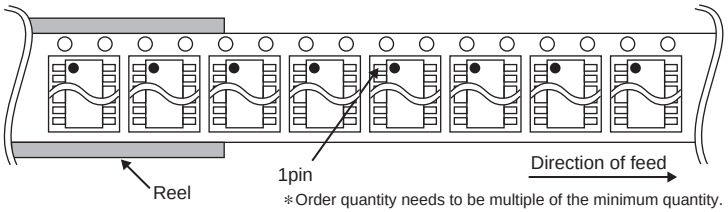
∗Order quantity needs to be multiple of the minimum quantity.

HSOP25



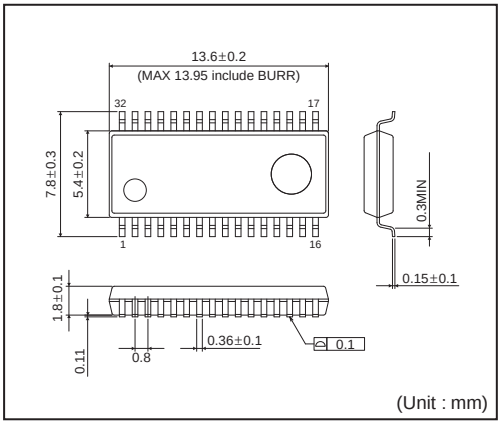
<Tape and Reel information>

Tape	Embossed carrier tape
Quantity	2000pcs
Direction of feed	E2 (The direction is the 1pin of product is at the upper left when you hold reel on the left hand and you pull out the tape on the right hand)



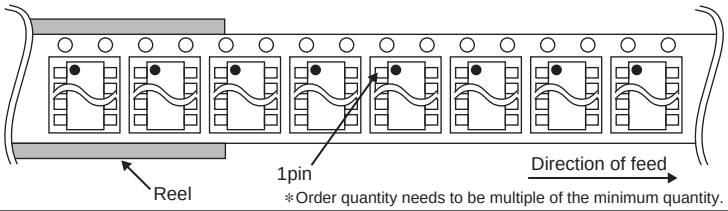
∗Order quantity needs to be multiple of the minimum quantity.

SSOP-A32



<Tape and Reel information>

Tape	Embossed carrier tape
Quantity	2000pcs
Direction of feed	E2 (The direction is the 1pin of product is at the upper left when you hold reel on the left hand and you pull out the tape on the right hand)



∗Order quantity needs to be multiple of the minimum quantity.

Notice

Precaution on using ROHM Products

1. Our Products are designed and manufactured for application in ordinary electronic equipments (such as AV equipment, OA equipment, telecommunication equipment, home electronic appliances, amusement equipment, etc.). If you intend to use our Products in devices requiring extremely high reliability (such as medical equipment (Note 1), transport equipment, traffic equipment, aircraft/spacecraft, nuclear power controllers, fuel controllers, car equipment including car accessories, safety devices, etc.) and whose malfunction or failure may cause loss of human life, bodily injury or serious damage to property ("Specific Applications"), please consult with the ROHM sales representative in advance. Unless otherwise agreed in writing by ROHM in advance, ROHM shall not be in any way responsible or liable for any damages, expenses or losses incurred by you or third parties arising from the use of any ROHM's Products for Specific Applications.

(Note1) Medical Equipment Classification of the Specific Applications

JAPAN	USA	EU	CHINA
CLASSⅢ	CLASSⅢ	CLASSⅡb	CLASSⅢ
CLASSⅣ		CLASSⅢ	

2. ROHM designs and manufactures its Products subject to strict quality control system. However, semiconductor products can fail or malfunction at a certain rate. Please be sure to implement, at your own responsibilities, adequate safety measures including but not limited to fail-safe design against the physical injury, damage to any property, which a failure or malfunction of our Products may cause. The following are examples of safety measures:
   [a] Installation of protection circuits or other protective devices to improve system safety
   [b] Installation of redundant circuits to reduce the impact of single or multiple circuit failure

3. Our Products are designed and manufactured for use under standard conditions and not under any special or extraordinary environments or conditions, as exemplified below. Accordingly, ROHM shall not be in any way responsible or liable for any damages, expenses or losses arising from the use of any ROHM's Products under any special or extraordinary environments or conditions. If you intend to use our Products under any special or extraordinary environments or conditions (as exemplified below), your independent verification and confirmation of product performance, reliability, etc, prior to use, must be necessary:
   [a] Use of our Products in any types of liquid, including water, oils, chemicals, and organic solvents
   [b] Use of our Products outdoors or in places where the Products are exposed to direct sunlight or dust
   [c] Use of our Products in places where the Products are exposed to sea wind or corrosive gases, including Cl_2, H_2S, NH_3, SO_2, and NO_2
   [d] Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
   [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
   [f] Sealing or coating our Products with resin or other coating materials
   [g] Use of our Products without cleaning residue of flux (even if you use no-clean type fluxes, cleaning residue of flux is recommended); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
   [h] Use of the Products in places subject to dew condensation

4. The Products are not subject to radiation-proof design.

5. Please verify and confirm characteristics of the final or mounted products in using the Products.

6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse. is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.

7. De-rate Power Dissipation (Pd) depending on Ambient temperature (Ta). When used in sealed area, confirm the actual ambient temperature.

8. Confirm that operation temperature is within the specified range described in the product specification.

9. ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

Precaution for Mounting / Circuit board design

1. When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.

2. In principle, the reflow soldering method must be used; if flow soldering method is preferred, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

Precautions Regarding Application Examples and External Circuits

1. If change is made to the constant of an external circuit, please allow a sufficient margin considering variations of the characteristics of the Products and external components, including transient characteristics, as well as static characteristics.

2. You agree that application notes, reference designs, and associated data and information contained in this document are presented only as guidance for Products use. Therefore, in case you use such information, you are solely responsible for it and you must exercise your own independent verification and judgment in the use of such information contained in this document. ROHM shall not be in any way responsible or liable for any damages, expenses or losses incurred by you or third parties arising from the use of such information.

Precaution for Electrostatic

This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of Ionizer, friction prevention and temperature / humidity control).

Precaution for Storage / Transportation

1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
   - [a] the Products are exposed to sea winds or corrosive gases, including Cl2, H2S, NH3, SO2, and NO2
   - [b] the temperature or humidity exceeds those recommended by ROHM
   - [c] the Products are exposed to direct sunshine or condensation
   - [d] the Products are exposed to high Electrostatic

2. Even under ROHM recommended storage condition, solderability of products out of recommended storage time period may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is exceeding the recommended storage time period.

3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.

4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

Precaution for Product Label

QR code printed on ROHM Products label is for ROHM's internal use only.

Precaution for Disposition

When disposing Products please dispose them properly using an authorized industry waste company.

Precaution for Foreign Exchange and Foreign Trade act

Since our Products might fall under controlled goods prescribed by the applicable foreign exchange and foreign trade act, please consult with ROHM representative in case of export.

Precaution Regarding Intellectual Property Rights

1. All information and data including but not limited to application example contained in this document is for reference only. ROHM does not warrant that foregoing information or data will not infringe any intellectual property rights or any other rights of any third party regarding such information or data. ROHM shall not be in any way responsible or liable for infringement of any intellectual property rights or other damages arising from use of such information or data.:

2. No license, expressly or implied, is granted hereby under any intellectual property rights or other rights of ROHM or any third parties with respect to the information contained in this document.

Other Precaution

1. This document may not be reprinted or reproduced, in whole or in part, without prior written consent of ROHM.

2. The Products may not be disassembled, converted, modified, reproduced or otherwise changed without prior written consent of ROHM.

3. In no event shall you use in any way whatsoever the Products and the related technical information contained in the Products or this document for any military purposes, including but not limited to, the development of mass-destruction weapons.

4. The proper names of companies or products described in this document are trademarks or registered trademarks of ROHM, its affiliated companies or third parties.

General Precaution

1. Before you use our Products, you are requested to carefully read this document and fully understand its contents. ROHM shall not be in any way responsible or liable for failure, malfunction or accident arising from the use of any ROHM's Products against warning, caution or note contained in this document.

2. All information contained in this document is current as of the issuing date and subject to change without any prior notice. Before purchasing or using ROHM's Products, please confirm the latest information with a ROHM sales representative.

3. The information contained in this document is provided on an "as is" basis and ROHM does not warrant that all information contained in this document is accurate and/or error-free. ROHM shall not be in any way responsible or liable for any damages, expenses or losses incurred by you or third parties resulting from inaccuracy or errors of or concerning such information.